



- ① Parasitics Influencing Switching in a Half Bridge
- ② Gate Driver Circuits
- ③ PCB layout - good practices

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A Typical DC Motor Drive

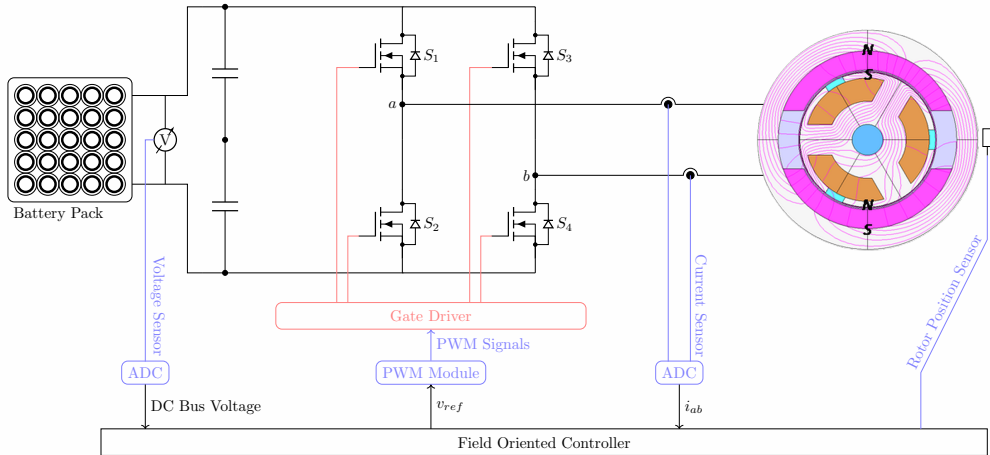


Figure: A typical DC motor drive.

Parasitics in a half-bridge

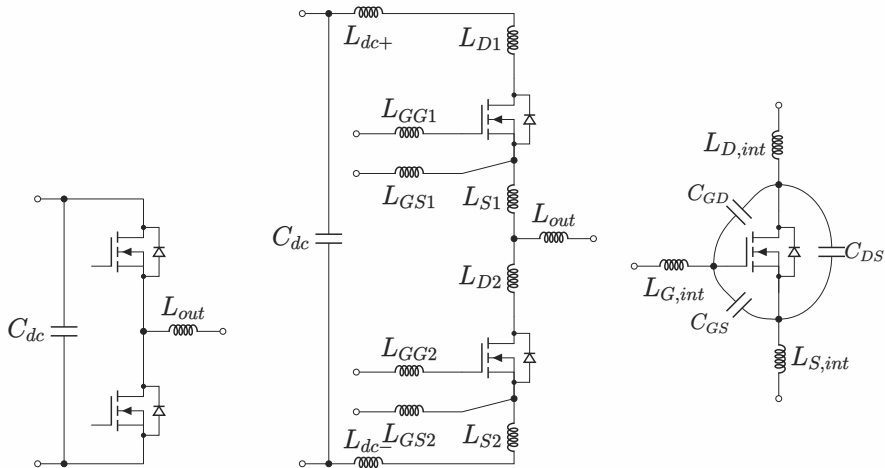


Figure: Parasitics in a half bridge.

Layout dependent inductance

Several sources of layout dependent parasitic inductances:

- DC link capacitors to the switches.
- Connection between the switches.
- Gate source connection with gate drivers.

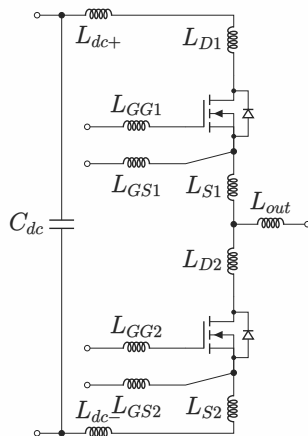


Figure: Layout dependent parasitics in a half bridge.

Layout dependent inductance

Reducing L_{dc+} and L_{dc-} using decoupling capacitors place close to the half bridge stage.

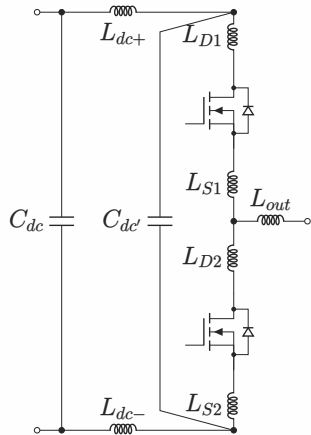


Figure: Using decoupling capacitors to reduce impact of L_{dc+} and L_{dc-} .

Layout dependent inductance

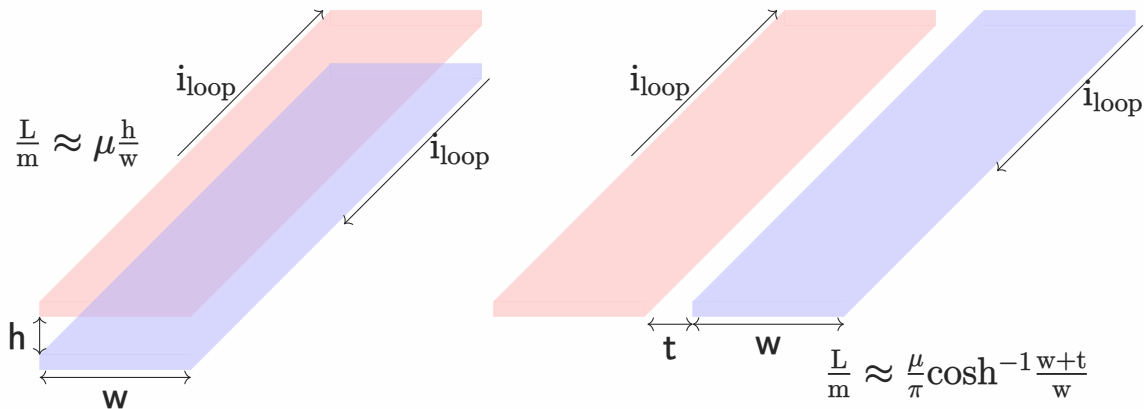


Figure: Parallel plate vs co-planar inductance [1].

Package dependent parasitics

- Parasitic capacitances
- Parasitic inductances

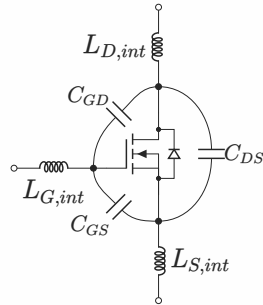


Figure: Parasitics in a typical MOSFET package.

Package dependent parasitics

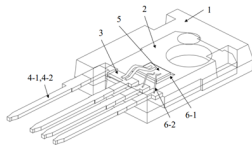


Figure: TO-247-4L [3].

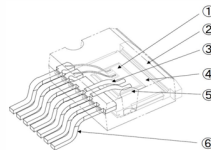


Figure: TO-263-7L [4].

Table: Loop inductance for different packages [5].

Package	Loop inductance [nH]
TO-247-4	≈ 15
TO-263-7	≈ 9

Parasitic capacitances

- C_{GS} determines how fast the switch starts conducting current.
- C_{GD} determines how fast the switch voltage changes.
- C_{DS} determines the losses incurred at turn-on. The energy stored in C_{DS} is lost when switch is shorted at turn on.

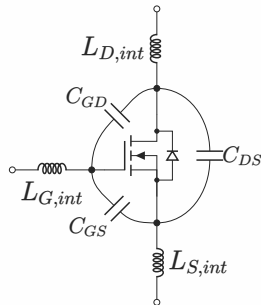


Figure: Package parasitics.

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HB gate driver - common elements

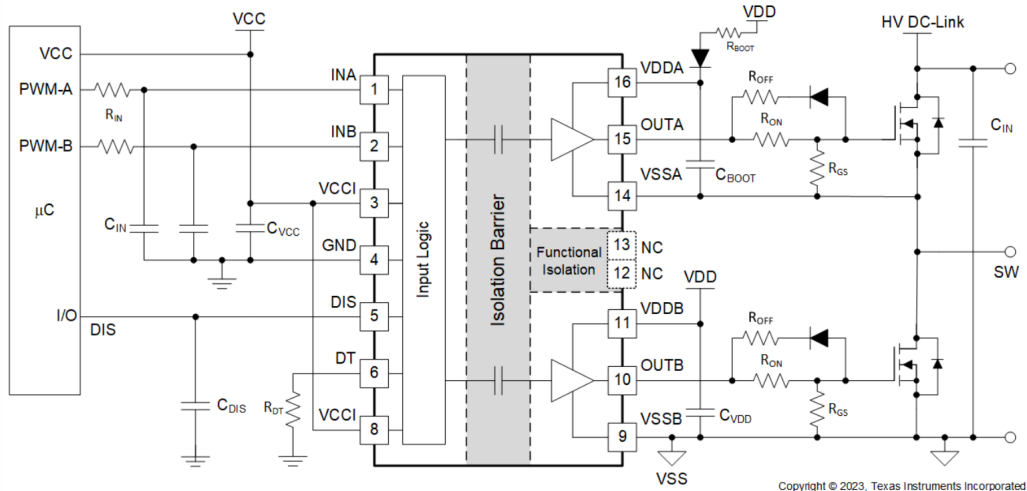


Figure: Common elements in a gate driver circuit. Source: [6].

HB gate driver - supply types

- Isolated supply.

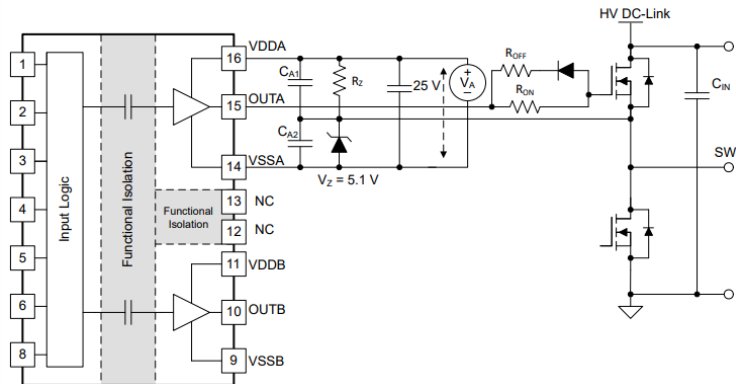


Figure: Gate driver using isolated supply. Source: [6].

HB gate driver - supply types

- Isolated supply.
- Bootstrap supply.

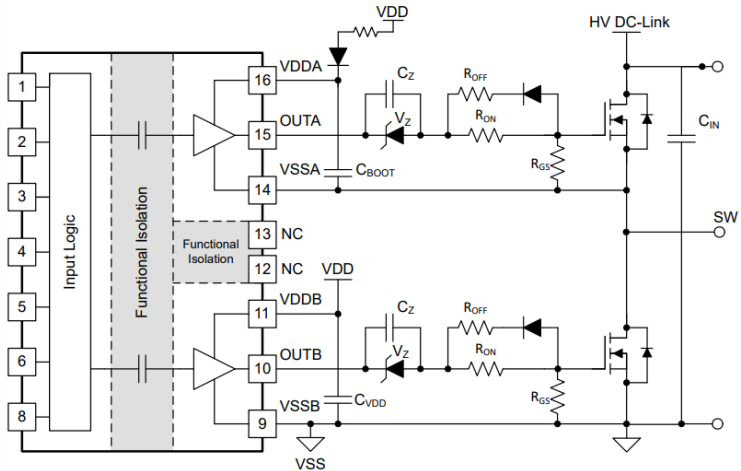


Figure: Gate driver using bootstrap supply. Source: [6].

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PCB layout - good practices

Some practices to improve circuit performance and EMI [7]:

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- Place bypass capacitors as close as possible to the components.

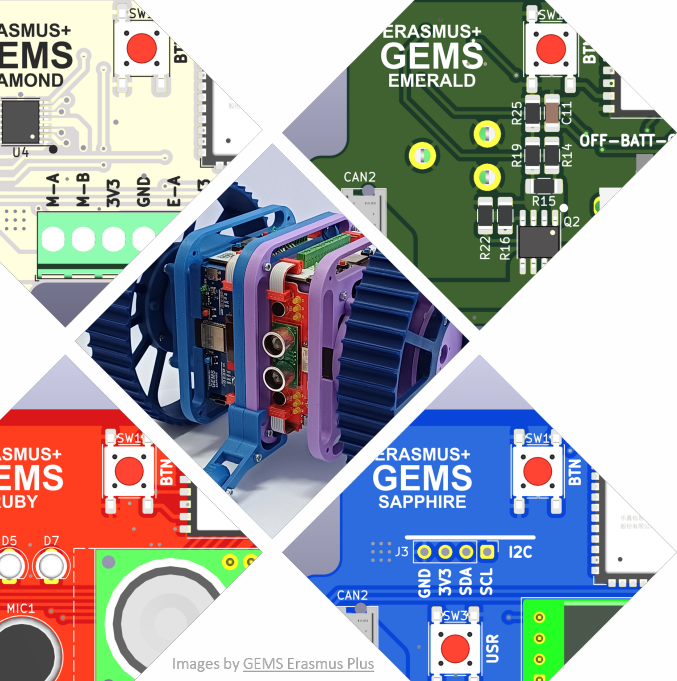
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- Reduce loop area as much as possible -> Keep high di/dt components close.
- Place bypass capacitors as close as possible to the components.
- Never cut ground below/above a signal/power path. More info -> [9].

Conclusion

- Parasitics in a half bridges.
- Gate driver circuits.
- Review of good layouting practices.



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Thank you for watching!

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